Company Overview

Customized Interconnect Solutions
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• Advanced Interconnections designs and manufactures customized interconnect solutions for semiconductor development and high reliability electronic applications
• IC sockets, package conversion adapters, and board to board connectors feature screw-machined terminals for field-proven performance and durability
• Made in America in our vertically integrated manufacturing facility in Rhode Island
• ISO 9001:2015 Certified & ITAR Registered
• Valued supplier to leading OEMs and contract manufacturers worldwide since 1982
Tool Box of Interconnect Technology

- Standard and modified components are combined to create customized solutions
  - Extensive tooling capability
  - Over 500 screw-machined terminal designs
  - Thousands of patterns and footprints
  - Variety of insulator (substrate) materials

- Collaborative application design assistance from experienced technical staff
  - Concept drawings, samples, prototypes
  - Signal Integrity (SI) simulation and modeling
Vertical Integration

• Swiss screw machines and CNC technology
• Precision drilling/routing, high speed injection molding, and polyimide film stamping
  – Economical options from prototype through production volumes
• Surface Mount Technology (SMT) center
  – Extensive convection reflow capability, solder ball attach, pick & place device attach, tape & reel packaging, electrical shorts/open test capabilities
• Complete process control
  – Automated optical inspection, laser scan microscope, customer-specific attribute measurement and verification
Precision Screw Machining

• Screw-machined pins & terminals for superior performance and durability
• Socket contact features redundant mating beams
  – Multi-finger contacts
• Extensive termination styles
  – Thru-hole, solder ball (SMT), solder preforms, press-fit, right angle, and cable-to-board mount
Solving Your Design Challenges

- Protect delicate or expensive devices by plugging them in after board processing
- Plan for field replacement, repair, or programming at point-of-use
- Board mounting and stacking
- Test, development, and validation
- Package conversion
- Automate pin loading
- Allow visibility of solder joints on both sides of the PCB
- Overcome device obsolescence
- Meet RoHS lead-free requirements
BGA Socketing Systems

- **0.50mm to 1.27mm pitch solutions**
  - BGA Socket Adapter System
  - Flip-Top™ BGA/LGA Test Socket
  - Lead-free to leaded BGA Interposers
  - Package Conversion
  - Footprint-specific Molded and FR-4 insulators

- **Proprietary solder ball technology**
  - Superior processing results and proven reliability
  - Lead-free and Tin/Lead solder ball options

- **Thousands of footprints in online database**
IC Socket & Adapters

• **Surface mount and thru-hole designs**
  – Screw-machined terminals with multi-finger contacts for long-term reliability

• **Molded, FR-4, and polyimide film insulators**

• **Standard and customized solutions**
  – Peel-A-Way® Removable Terminal Carriers
  – PGA Sockets and Adapters
  – DIP & SIP Sockets and Adapters
  – Image Sensor Sockets
  – Application-specific designs
Board to Board Connectors

- **Linear and non-linear configurations**
  - Surface mount, thru-hole, and cable mount designs
  - Molded, FR-4, and polyimide film insulators
  - Prototype to production volumes
  - Standard and customized designs

- **Peel-A-Way® Removable Carriers**
  - Complete solder joint visibility

- **B2B® SMT Connectors**
  - High density 1.00mm pitch board stacking

- **Mezza-pede® SMT Connectors**
  - Low profile, 1.00mm pitch
Mezza-pede® SMT Connectors

• **Typical Applications**
  – Connect micro PC boards
  – Connect mezzanine and daughter cards
  – Power connectors in tunable lasers

• **Field-proven Reliability**
  – Millions installed worldwide
  – Screw-machined, robust pin-in-socket design on 1.00mm pitch
  – Passes 20-Day Mixed Flowing Gas (MFG) test
  – Pick-and-place covers protect delicate pin field and facilitate automated board assembly

• **Standard and custom designs available**
Adapters & Interposers

- Standard and custom IC package conversion
- Thru-hole to thru-hole, SMT to thru-hole, and SMT to SMT
  - SOIC to DIP
  - QFP to PGA
  - Micro-BGA to BGA
  - PLCC to PGA
  - BGA to QFP
- Application-specific designs
  - Adapters can include multiple devices and components
“Interconnect solutions with superior reliability and technologically advanced features, customized to solve difficult design problems.”

That’s the Advanced® Difference.